

- substrate including a conductive surface on an underside of the planar substrate;
- a heat sink coupled to the electronics assembly, the heat sink comprising a base portion configured to thermally couple to the at least one electronic component when the heat sink is coupled to the electronic assembly; and
- a conductive enclosure forming an enclosed volume around the electronics assembly, the enclosure comprising a first opening configured to fit around the heat sink, at least one second opening formed in the conductive enclosure spaced from the first opening, wherein the conductive cover is in electrical contact with the conductive surface and the heat sink, and the second opening is located at the top of the display, the first opening is located at the base of the display.
- 20.** The electronics enclosure of claim **19**, further comprising an internal space under the display, the first opening open to the internal space.

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